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Molding Type Module IGBT, 2-in-1 Package, 600 V and 400 A

Double INT-A-PAK

RoHS COMPLIANT

FEATURES

- Low $V_{CE(on)}$ trench IGBT technology
- Low switching losses
- 5 µs short circuit capability
- $V_{CE(on)}$ with positive temperature coefficient
- Maximum junction temperature 175 °C
- Low inductance case
- Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

PRODUCT SUMMARY	
V_{CES}	600 V
I_C at T_C = 80 °C	400 A
$V_{CE(on)}$ (typical) at I_C = 400 A, 25 °C	1.60 V
Speed	8 kHz to 30 kHz
Package	Double INT-A-PAK
Circuit	Half bridge

TYPICAL APPLICATIONS

- UPS
- Switching mode power supplies
- Electronic welders

DESCRIPTION

Vishay's IGBT power module provides ultralow conduction loss as well as short circuit ruggedness. It is designed for applications such as UPS and SMPS.

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	V_{CES}		600	V
Gate to emitter voltage	V_{GES}		± 20	
Collector current	I_C	T_C = 25 °C	530	A
		T_C = 80 °C	400	
Pulsed collector current	I_{CM} (1)	t_p = 1 ms	800	
Diode continuous forward current	I_F		400	
Diode maximum forward current	I_{FM}		800	
Maximum power dissipation	P_D	T_J = 175 °C	1600	W
Short circuit withstand time	t_{SC}	T_J = 125 °C	5	µs
I^2t-value, diode	I^2t	V_R = 0 V, t = 10 ms, T_J = 125 °C	10 900	A^2s
RMS isolation voltage	V_{ISOL}	f = 50 Hz, t = 1 min	2500	V

Note

(1) Repetitive rating: pulse width limited by maximum junction temperature.

IGBT ELECTRICAL SPECIFICATIONS (T_C = 25 °C unless otherwise noted)						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNITS**
Collector to emitter breakdown voltage	$V_{(BR)CES}$	V_{GE} = 0 V, I_C = 2 mA, T_J = 25 °C	600	-	-	V
Collector to emitter saturation voltage	$V_{CE(on)}$	V_{GE} = 15 V, I_C = 400 A, T_J = 25 °C	-	1.6	2.05	
		V_{GE} = 15 V, I_C = 400 A, T_J = 175 °C	-	2.0	-	
Gate to emitter threshold voltage	$V_{GE(th)}$	V_{CE} = V_{GE}, I_C = 4 mA, T_J = 25 °C	4.0	-	6.5	
Zero gate voltage collector current	I_{CES}	V_{CE} = V_{CES}, V_{GE} = 0 V, T_J = 25 °C	-	-	5.0	mA
Gate to emitter leakage current	I_{GES}	V_{GE} = V_{GES}, V_{CE} = 0 V, T_J = 25 °C	-	-	400	nA

SWITCHING CHARACTERISTICS						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNITS**
Turn-on delay time	$t_{d(on)}$	V_{CC} = 400 V, I_C = 400 A, R_g = 1.3 Ω, V_{GE} = ± 15 V, T_J = 25 °C	-	35	-	ns
Rise time	t_r		-	70	-	
Turn-off delay time	$t_{d(off)}$		-	180	-	
Fall time	t_f		-	75	-	
Turn-on switching loss	E_{on}		-	14.1	-	mJ
Turn-off switching loss	E_{off}		-	10.0	-	
Turn-on delay time	$t_{d(on)}$	V_{CC} = 400 V, I_C = 400 A, R_g = 1.3 Ω, V_{GE} = ± 15 V, T_J = 175 °C	-	37	-	ns
Rise time	t_r		-	72	-	
Turn-off delay time	$t_{d(off)}$		-	220	-	
Fall time	t_f		-	84	-	
Turn-on switching loss	E_{on}		-	23.2	-	mJ
Turn-off switching loss	E_{off}		-	16.8	-	
Input capacitance	C_{ies}	V_{GE} = 0 V, V_{CE} = 30 V, f = 1.0 MHz	-	30.8	-	nF
Output capacitance	C_{oes}		-	2.12	-	
Reverse transfer capacitance	C_{res}		-	0.92	-	
SC data	I_{SC}	t_{sc} ≤ 5 µs, V_{GE} = 15 V, T_J = 125 °C, V_{CC} = 360 V, V_{CEM} ≤ 600 V	-	TBD	-	A
Internal gate resistance	R_{gint}		-	1.3	-	Ω
Stray inductance	L_{CE}		-	-	20	nH
Module lead resistance, terminal to chip	$R_{CC'+EE'}$	T_C = 25 °C	-	0.35	-	mΩ

DIODE ELECTRICAL SPECIFICATIONS (T_C = 25 °C unless otherwise noted)							
PARAMETER	**SYMBOL**	**TEST CONDITIONS**		**MIN.**	**TYP.**	**MAX.**	**UNITS**
Diode forward voltage	V_F	I_F = 400 A	T_J = 25 °C	-	1.38	1.80	V
			T_J = 125 °C	-	1.41	-	
Diode reverse recovery charge	Q_{rr}	I_F = 400 A, V_R = 300 V, dI/dt = -7000 A/µs, V_{GE} = -15 V	T_J = 25 °C	-	15.5	-	µC
			T_J = 125 °C	-	28.5	-	
Diode peak reverse recovery current	I_{rr}		T_J = 25 °C	-	265	-	A
			T_J = 125 °C	-	335	-	
Diode reverse recovery energy	E_{rec}		T_J = 25 °C	-	3.5	-	mJ
			T_J = 125 °C	-	7.5	-	

THERMAL AND MECHANICAL SPECIFICATIONS							
PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Operating junction temperature range		T_J		-	-	175	°C
Storage temperature range		T_{Stg}		-40	-	125	
Junction to case per ½ module	IGBT	R_{thJC}		-	-	0.094	K/W
	Diode			-	-	0.158	
Case to sink		R_{thCS}	Conductive grease applied	-	0.035	-	
Mounting torque			Power terminal screw: M6	2.5 to 5.0			Nm
			Mounting screw: M6	3.0 to 5.0			
Weight				300			g

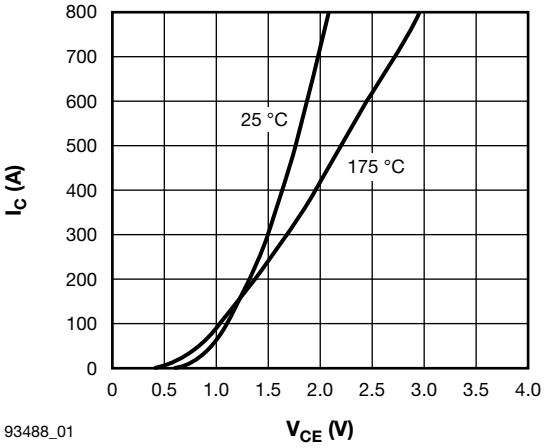


Fig. 1 - IGBT Typical Output Characteristics
V_{GE} = 15 V

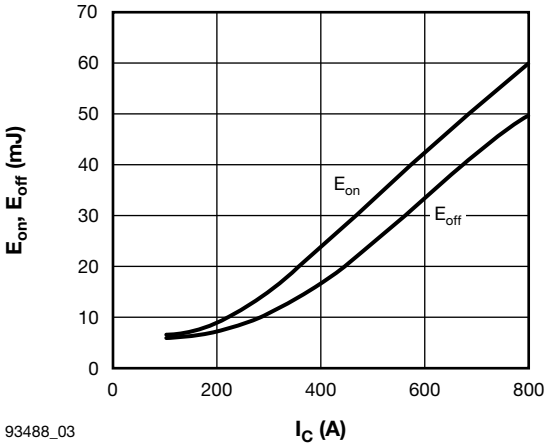


Fig. 3 - IGBT Switching Loss vs. Collector Current
V_{CC} = 600 V, R_g = 1.3 Ω, V_{GE} = ± 15 V, T_J = 175 °C

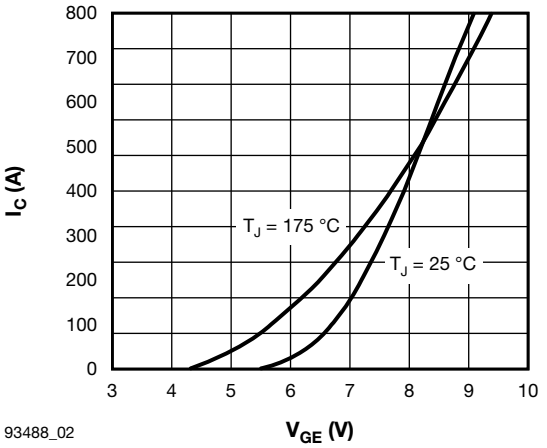


Fig. 2 - IGBT Typical Transfer Characteristics
V_{CE} = 20 V

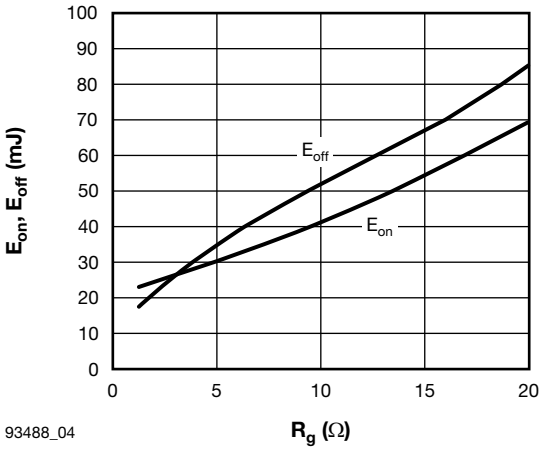


Fig. 4 - Switching Loss vs. Gate Resistor
V_{CE} = 600 V, I_C = 400 A, V_{GE} = ± 15 V, T_J = 175 °C

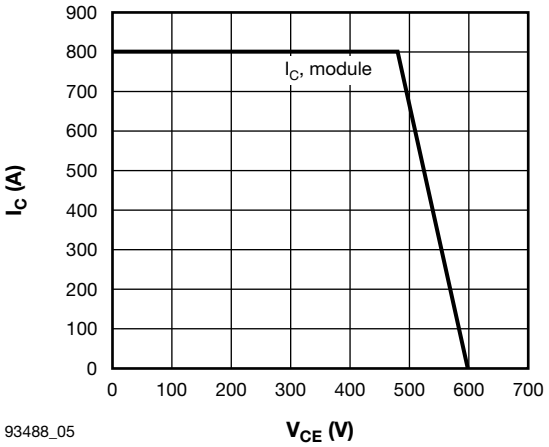


Fig. 5 - RBSOA
R_g = 1.3 Ω, V_{GE} = ± 15 V, T_J = 175 °C

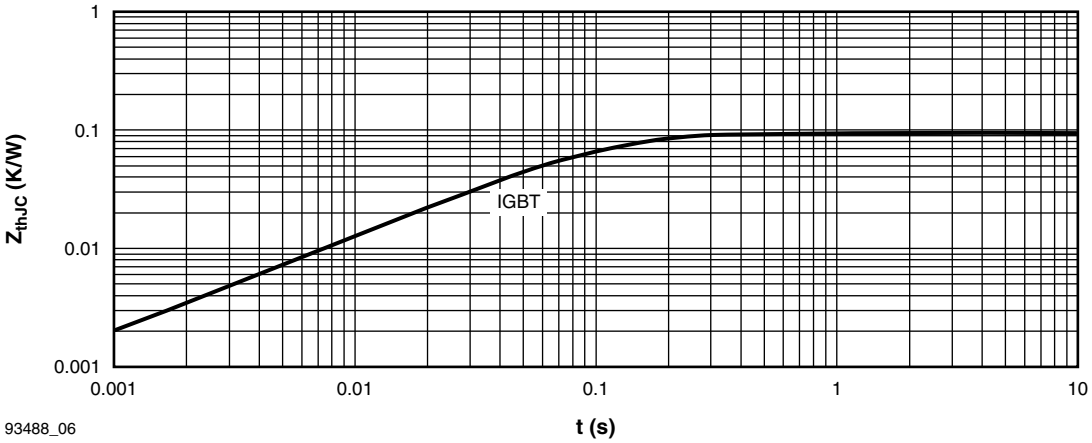


Fig. 6 - IGBT Transient Thermal Impedance

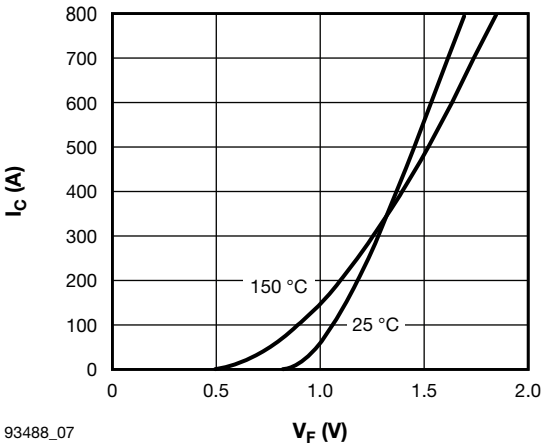


Fig. 7 - Forward Characteristics of Diode

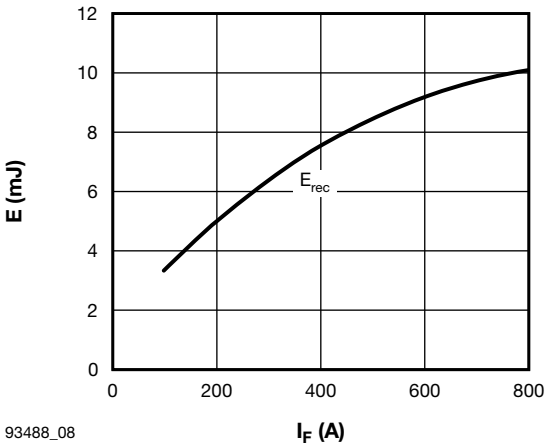


Fig. 8 - Diode Switching Loss vs. I_F
V_{CC} = 600 V, R_g = 1.3 Ω, V_{GE} = - 15 V, T_J = 125 °C

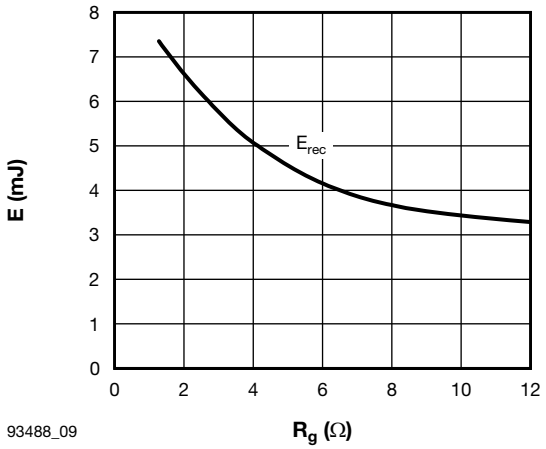


Fig. 9 - Diode Switching Loss vs. Gate Resistance
V_{CC} = 600 V, I_C = 400 A, V_{GE} = - 15 V, T_J = 125 °C

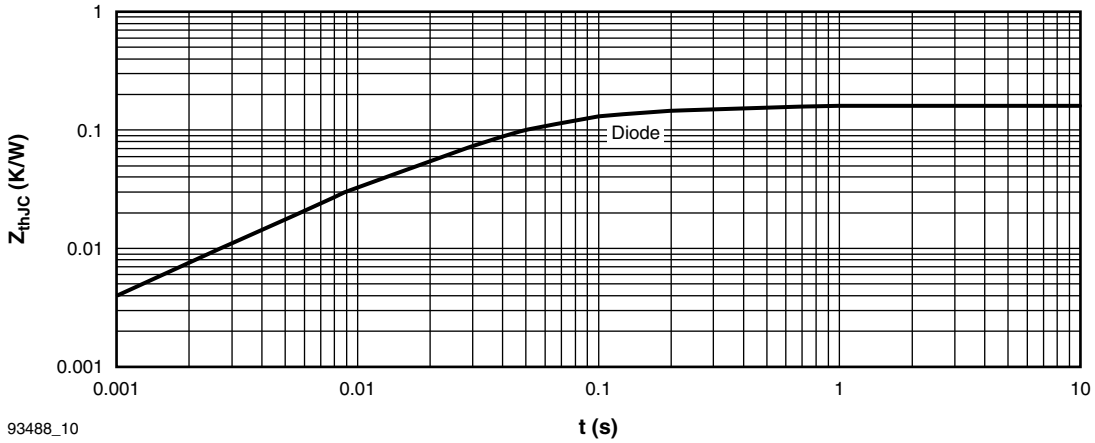
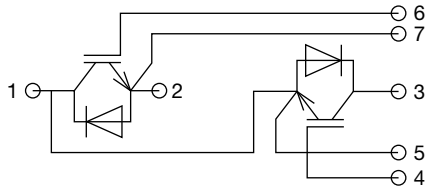


Fig. 10 - Diode Transient Thermal Impedance

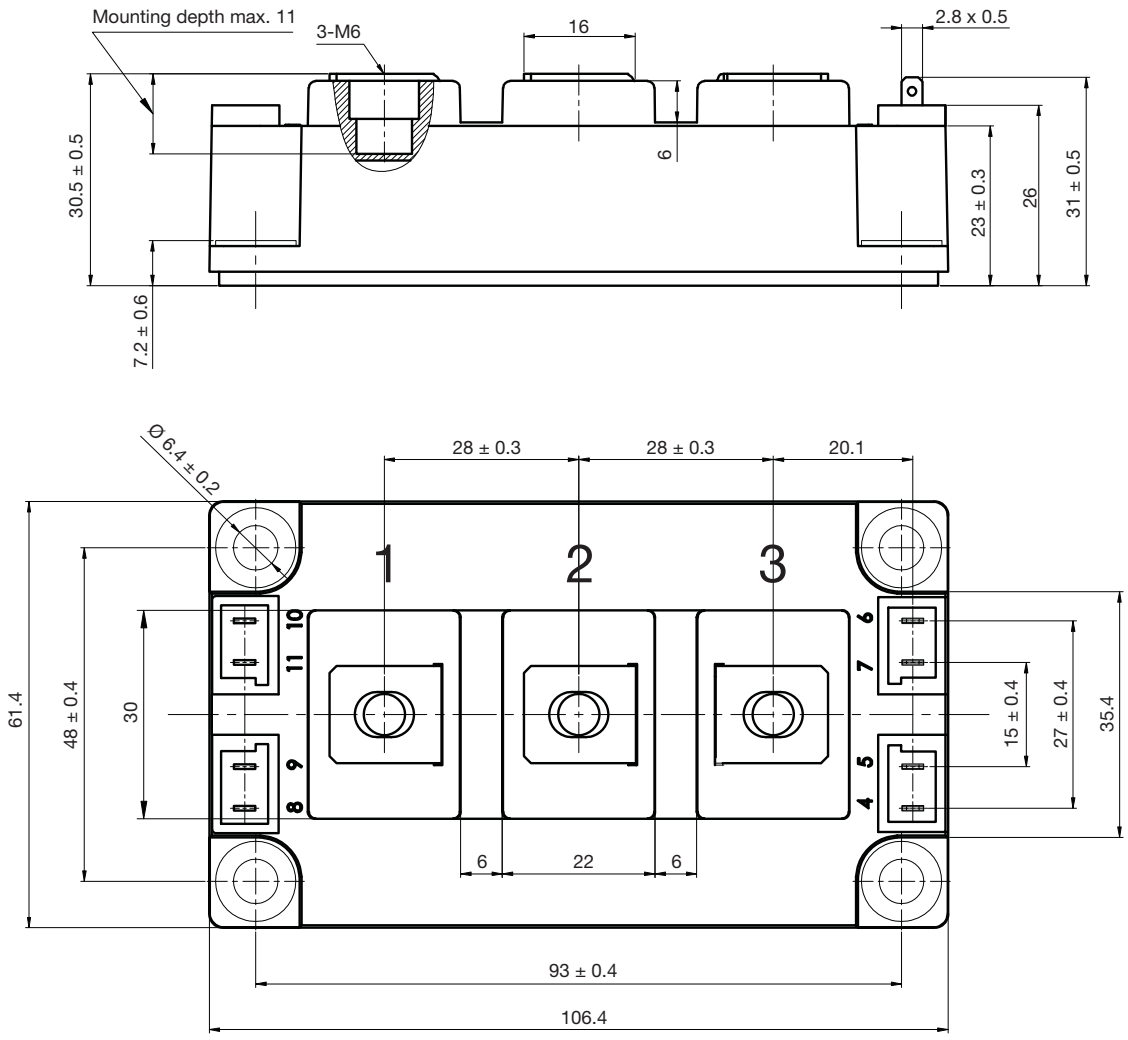
CIRCUIT CONFIGURATION



LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95525

Double INT-A-PAK

DIMENSIONS in millimeters (inches)



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